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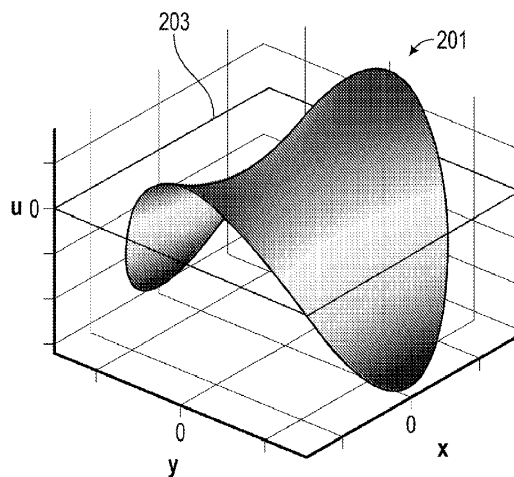


FIG. 2A

(57) Abstract: Methods, apparatuses, and computer program products are provided for simulating backside layer deposition. Deposition of a backside layer stack may mitigate wafer bow that varies in orthogonal directions. Each of the backside layers may be deposited by a backside deposition apparatus.

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